

7.62mm (0.3 INCH) SINGLE COLOR DOT MATRIX DISPLAY

Part Number: TA03-11ET

High Efficiency Red

PAGE: 1 OF 6

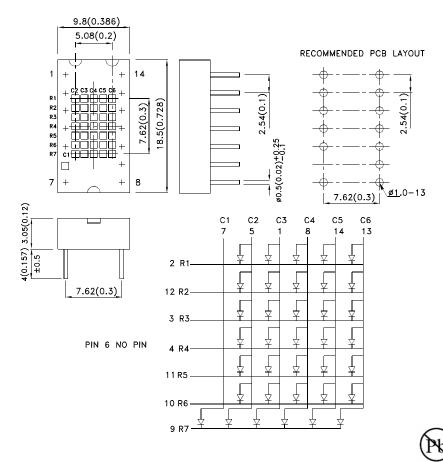
Features

- 0.3 inch matrix height.
- Low current operation.
- Stackable vertically and horizontally.
- Easy mounting on P.C. boards or sockets.
- Mechanically rugged.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram





1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.

2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAE9742 REV NO: V.2A DATE: JUN/20/2013

APPROVED: WYNEC CHECKED: Joe Lee DRAWN: Y.Liu

Selection Guide

Part No.	Dice	Lens Type	lv (ucd) [1] @ 10mA		Description
			Min.	Тур.	•
TA03-11ET	High Efficiency Red (GaAsP/GaP)	Red Transparent	2200	5600	Column Anode
			*900	*1800	

Note:

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2.0	2.5	V	IF=20mA
lR	Reverse Current	High Efficiency Red		10	uA	V _R =5V

Notes:

- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

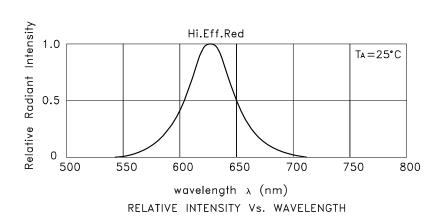
Parameter	High Efficiency Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating / Storage Temperature	Storage Temperature -40°C To +85°C		
Lead Solder Temperature[2]	ad Solder Temperature[2] 260°C For 3-5 Seconds		

- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.

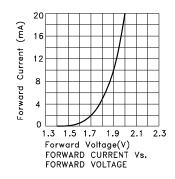
SPEC NO: DSAE9742 **REV NO: V.2A** DATE: JUN/20/2013 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED:** Joe Lee DRAWN: Y.Liu

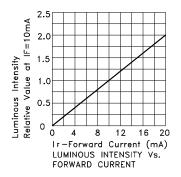
^{1.}Luminous intensity/ luminous Flux: +/-15%.

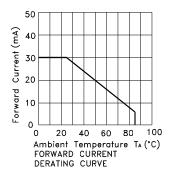
^{*}Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

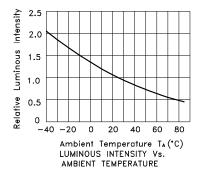


High Efficiency Red TA03-11ET





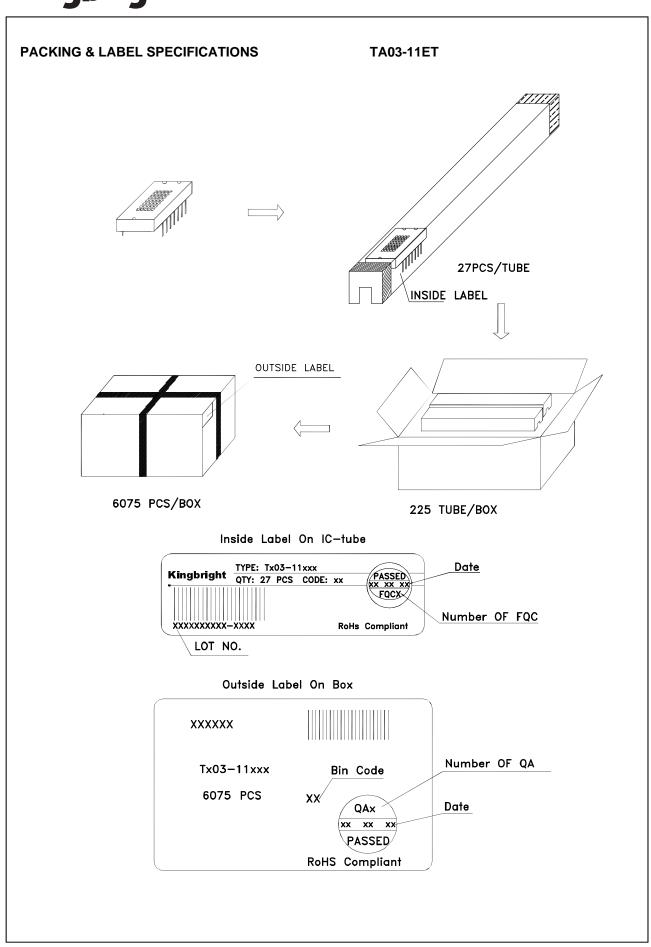




PAGE: 3 OF 6

SPEC NO: DSAE9742 REV NO: V.2A DATE: JUN/20/2013

APPROVED: WYNEC CHECKED: Joe Lee DRAWN: Y.Liu



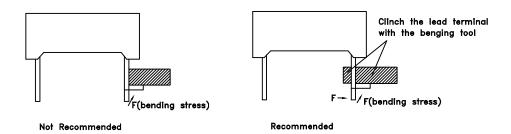
SPEC NO: DSAE9742 APPROVED: WYNEC REV NO: V.2A CHECKED: Joe Lee DATE: JUN/20/2013 DRAWN: Y.Liu

PAGE: 4 OF 6

THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



Installation

- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.





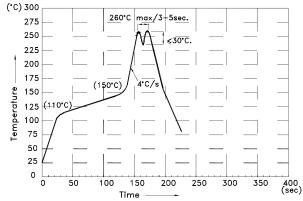
PAGE: 5 OF 6

SPEC NO: DSAE9742 REV NO: V.2A DATE: JUN/20/2013

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DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top-surface temperature should be kept below $105^{\circ}C$

5.No more than once.

Soldering General Notes:

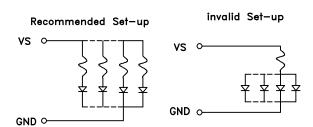
- 1. Through—hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

- 1.Protective current—limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



Detailed application notes are listed on our website. http://www.kingbright.com/application_notes

SPEC NO: DSAE9742 REV NO: V.2A DATE: JUN/20/2013 PAGE: 6 OF 6
APPROVED: WYNEC CHECKED: Joe Lee DRAWN: Y.Liu